



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE75242-ESH	Issued	14. May 2021
MA#	MA003348018		
Package	PG-TSDSO-24-21	Weight*	111.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27625	27625
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11302	
	non noble metal	copper	7440-50-8	51.392	45.90	47.10	458910	470918
wire	non noble metal	copper	7440-50-8	0.810	0.72	0.72	7235	7235
encapsulation	organic material	carbon black	1333-86-4	0.150	0.13		1344	
	plastics	epoxy resin	-	5.869	5.24		52404	
	inorganic material	silicondioxide	60676-86-0	44.140	39.42	44.79	394153	447901
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25182	25182
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11421	11421
glue	plastics	epoxy resin	-	0.190	0.17		1701	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8017	9718
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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